



PNP PRE-BIASED (R1=R2) SMALL SIGNAL TRANSISTOR IN DFN1006

Product Summary

Part Number	R1 (NOM)	R2 (NOM)	Marking
DDTA144ELP	47kΩ	47kΩ	P2

Features

- Epitaxial Planar Die Construction
- Ultra-Small Leadless Surface Mount Package
- Ideally Suited for Automated Assembly Processes
- Totally Lead Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

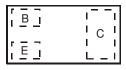
X1-DFN1006-3

Mechanical Data

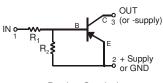
- Case: X1-DFN1006-3
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish NiPdAu.
- Solderable per MIL-STD-202, Method 208 @4
- Weight: 0.0009 grams (Approximate)



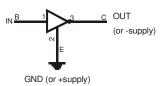
Bottom View



Top View Pin-Out



Device Symbol



Equivalent Inverter Circuit

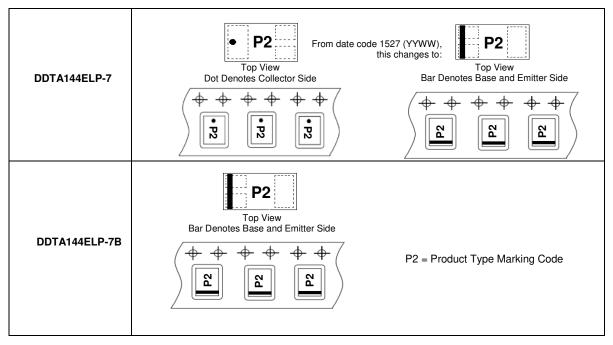
Ordering Information (Note 4)

Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
DDTA144ELP-7	P2	7	8	3,000
DDTA144ELP-7B	P2	7	8	10,000

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com.

Marking Information





Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Supply Voltage	V _{CC}	-50	V
Input Voltage	V _{IN}	+10 to -40	V
Output Current (Io)	I _{C(MAX)}	-200	mA

Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P _D	250	mW
Power Deration above +25°C	P _{der}	2	mW/°C
Thermal Resistance, Junction to Ambient Air (Note 5) (Equivalent to one heated junction of PNP)	$R_{ hetaJA}$	500	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Off Characteristics (Notes 6 & 7)						
Collector-Base Breakdown Voltage	BV_CBO	-50	_	_	V	$I_C = -10\mu A, I_E = 0$
Collector-Emitter Breakdown Voltage	BV _{CEO}	-50		_	V	$I_{C} = -1 \text{mA}, I_{B} = 0$
Emitter-Base Breakdown Voltage	BV _{EBO}	-4.5		_	V	$I_E = -100 \mu A, I_C = 0$
Collector Cutoff Current	I _{CEX}	_	_	-100	nA	$V_{CE} = -50V$, $V_{EB(OFF)} = 3V$
Base Cutoff Current (I _{BEX})	I_{BL}			-60	μΑ	$V_{CE} = -50V$, $V_{EB(OFF)} = 3V$
Collector-Base Cut Off Current	I _{CBO}			-100	nA	$V_{CB} = -50V, I_{E} = 0$
Collector-Emitter Cut Off Current, IO(off)	I _{CES}			-100	nA	$V_{CE} = -50V, I_B = 0$
Emitter-Base Cut Off Current	I _{EBO}			-100	μΑ	$V_{EB} = -4V, I_{C} = 0$
Input Off Voltage	V _{I(off)}	-300	_	_	mV	$V_{CC} = -5V$, $I_{O} = -100uA$
On Characteristics (Notes 6 & 7)						
Input-On Voltage	V _{I(on)}	_	_	-3	V	$V_O = -0.3V$, $I_O = -5mA$
Input Current	lı			-180	μΑ	$V_1 = -5V$
		90		_	_	$V_{CE} = -5V, I_{C} = -2.5mA$
		120		_	_	$V_{CE} = -5V$, $I_C = -5mA$
DC Current Gain	h	150		_	_	$V_{CE} = -5V, I_{C} = -10mA$
Do Guirent Gain	h _{FE}	100		_	_	$V_{CE} = -5V, I_{C} = -100mA$
		180		_	_	$V_{CE} = -5V, I_{C} = -200mA$
		250	_	_	_	$V_{CE} = -5V, I_{C} = -300mA$
Output On Voltage	Vac			-150	mV	$I_{I} = -1 \text{mA}, I_{O} = -10 \text{mA}$
(Collector-Emitter Saturation Voltage)	$V_{O(on)}$	_		-800	mV	$I_1 = -1 \text{mA}, I_0 = -40 \text{mA}$
Input Resistance	R1	33	47	61	kΩ	_
Resistance Ratio	(R2/R1)	0.8	1	1.2	_	_
Small Signal Characteristics						
Current Gain-Bandwidth Product	f⊤		250	_	MHz	$V_{CE} = -10V$, $I_E = -5mA$, $f = 100 \text{ MHz}$

- 5. For the device mounted on minimum recommended pad layout 1oz copper that is on a single-sided 1.6mm FR4 PCB; device is measured under still air conditions whilst operating in steady state condition. The entire exposed collector pad is attached to the heatsink. 6. Measured under pulsed conditions. Pulse width $\leq 300 \mu s$. Duty cycle $\leq 2\%$.
- 7. Guaranteed by design.



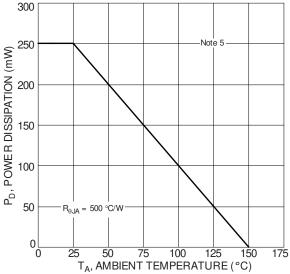


Fig. 1 Power Dissipation vs. Ambient Temperature

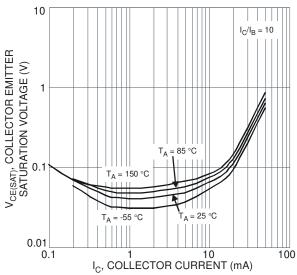


Fig. 3 Typical Collector Emitter Saturation Voltage vs. Collector Current

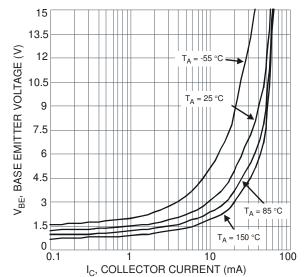


Fig. 5 Typical Base Emitter Voltage vs. Collector Current

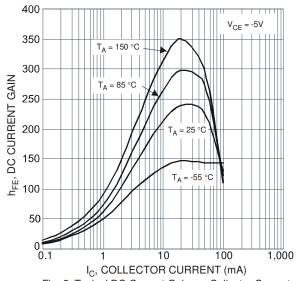


Fig. 2 Typical DC Current Gain vs. Collector Current

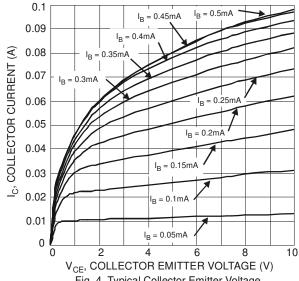


Fig. 4 Typical Collector Emitter Voltage vs. Collector Current

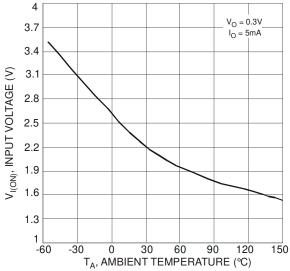
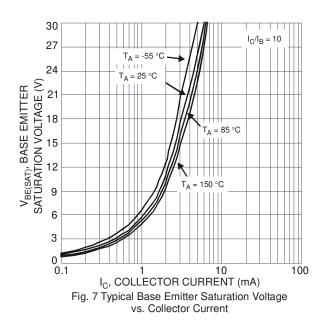


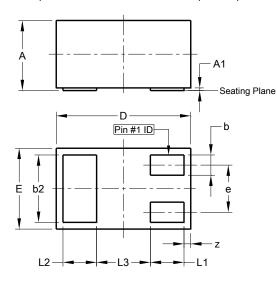
Fig. 6 Typical Input Voltage vs. Ambient Temperature





Package Outline Dimensions

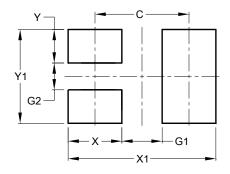
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



X1-DFN1006-3					
Dim	Min	Max	Тур		
Α	0.47	0.53	0.50		
A1	0.00	0.05	0.03		
b	0.10	0.20	0.15		
b2	0.45	0.55	0.50		
D	0.95	1.075	1.00		
Е	0.55	0.675	0.60		
е	ı	-	0.35		
L1	0.20	0.30	0.25		
L2	0.20	0.30	0.25		
L3	-	-	0.40		
Z	0.02	0.08	0.05		
All Dimensions in mm					

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
С	0.70
G1	0.30
G2	0.20
Х	0.40
X1	1.10
Y	0.25
Y1	0.70



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